GD200HFT60C8S IGBT Module

STARPOWER

SEMICONDUCTOR™

IGBT

GD200HFT60C8S

Preliminary

Molding Type Module

600V/200A 2 in one-package

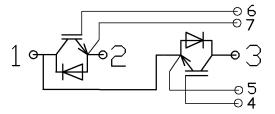


General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

Features

- Low V_{CE(sat)} trench IGBT technology
- Low switching losses
- Maximum junction temperature 175°C
- 5µs short circuit capability
- Square RBSOA
- ullet $V_{CE(sat)}$ with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



Equivalent Circuit Schematic

Typical Applications

- AC inverter drives
- Switching mode power supplies
- Electronic welders

Absolute Maximum Ratings T_C=25 °C unless otherwise noted

Symbol	Description	GD200HFT60C8S	Units	
V_{CES}	Collector-Emitter Voltage	600	V	

GD200HFT60C8S IGBT Module

Symbol	Description	GD200HFT60C8S	Units
V_{GES}	Gate-Emitter Voltage	±20	V
T	Collector Current @ T _C =25°C	350	Δ.
I_{C}	@ T _C =80°C	200	A
$I_{CM(1)}$	Pulsed Collector Current t _p =1ms	400	A
I_{F}	Diode Continuous Forward Current	200	A
I_{FM}	Diode Maximum Forward Current	400	A
P_{D}	Maximum power Dissipation @ $T_j=175^{\circ}C$	811	W
T_{SC}	Short Circuit Withstand Time @ T _j =125°C	10	μs
$T_{\rm j}$	Operating Junction Temperature	-40 to +175	$^{\circ}\!\mathbb{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\!\mathbb{C}$
I ² t-value,Diode	$V_R=0V,t=10$ ms, $T_j=125$ °C	4050	A^2s
V _{ISO}	Isolation Voltage RMS,f=50Hz,t=1min	2500	V
Mounting Torque	Power Terminal Screw:M5	2.5 to 5.0	N.m
Mounting Torque	Mounting Screw:M6	3.0 to 6.0	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT T_C =25 $^{\circ}$ C unless otherwise noted

Off Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter	$V_{GE}=0V, I_{C}=500\mu A,$	600			17
	Breakdown Voltage	V_{GE} =0V, I_{C} =500 μ A, T_{j} =25 $^{\circ}$ C	600			·
I _{CES}	Collector Cut-Off Current	$V_{\text{CE}}=V_{\text{CES}}, V_{\text{GE}}=0V,$			100	
		T _j =25℃		100	μΑ	
I_{GES}	Gate-Emitter Leakage	$V_{\text{GE}}=V_{\text{GES}}, V_{\text{CE}}=0V,$		200		nA
	Current	T _j =25℃				

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
$V_{\text{GE(th)}}$	Gate-Emitter Threshold Voltage	I_{C} =2.0mA, V_{CE} = V_{GE} , T_{j} =25°C	4.0	4.5	6.5	V
V _{CE(sat)}	Collector to Emitter	I_{C} =200A, V_{GE} =15V, T_{j} =25°C		2.1	V	
	Saturation Voltage	I_{C} =200A, V_{GE} =15V, T_{j} =175°C				V

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	V_{CC} =300V, I_{C} =200A,		24		ns
t _r	Rise Time	$R_G=2.3\Omega, V_{GE}=\pm 15V,$		59		ns
$t_{d(off)}$	Turn-Off Delay Time	T _j =25℃		106		ns

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t_{f}	Fall Time		69		ns
E_{on}	Turn-On Switching Loss	V_{CC} =300V, I_{C} =200A, R_{G} =2.3 Ω , V_{GE} = \pm 15V,	6.9		mJ
$E_{\rm off}$	Turn-Off Switching Loss	T _j =25°C	5.1		mJ
t _{d(on)}	Turn-On Delay Time		28		ns
t _r	Rise Time		62		ns
$t_{d(off)}$	Turn-Off Delay Time	V 200VI 200A	131		ns
$t_{\rm f}$	Fall Time	$V_{CC}=300V,I_{C}=200A,$ $R_{G}=2.3\Omega,V_{GE}=\pm 15V,$	88		ns
Eon	Turn-On Switching Loss	$T_{j}=175^{\circ}C$	9.6		mJ
E _{off}	Turn-Off Switching Loss		7.3		mJ
Cies	Input Capacitance		15.4		nF
C _{oes}	Output Capacitance	V _{CE} =25V,f=1MHz,	1.2		nF
C _{res}	Reverse Transfer Capacitance	V_{GE} =0 V	0.6		nF
I_{SC}	SC Data	$t_{S^{C}} \leq 10 \mu s, V_{GE} = 15 V,$ $T_{j} = 125 ^{\circ}\text{C}, V_{CC} = 360 V,$ $V_{CEM} \leq 600 V$	TBD		A
L _{CE}	Stray Inductance			26	nН
R _{CC'+EE'}	Module Lead Resistance, Terminal to Chip	T _C =25℃	0.62		mΩ

Electrical Characteristics of DIODE $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Condit	ions	Min.	Тур.	Max.	Units
17	Diode Forward	I _F =200A	T _j =25°C		1.4		V
V_{F}	Voltage	I _F =200A	T _j =125℃		1.3		\ \ \
0	Diode Reverse	I_F =200A, V_R =300V, I_S 40/dt=-4000A/ I_S 40, I_S 70 I	T _j =25°C		12.1		μС
Q_r	Recovery Charge		T _j =125℃		19.7		
	Diode Peak		T _j =25℃		154		
I_{RM}	Reverse Recovery Current		T _j =125℃		188		A
E_{rec}	Reverse Recovery	V_{GE} =-15V	T _j =25°C		2.9		m I
	Energy		T _j =125℃		4.1		mJ

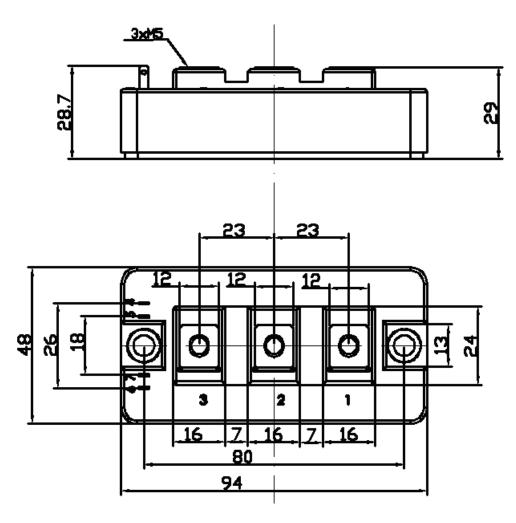
Thermal Characteristics

Symbol	Parameter		Max.	Units
$R_{\theta JC}$	Junction-to-Case (IGBT Part, per 1/2 Module)		0.185	K/W
$R_{ heta JC}$	Junction-to-Case (DIODE Part, per 1/2 Module)		0.296	K/W
$R_{ heta JC}$	Case-to-Sink (Conductive grease applied)	0.046		K/W
Weight	Weight of Module	200		g

GD200HFT60C8S **IGBT Module**

Package Dimension

Dimensions in Millimeters



GD200HFT60C8S IGBT Module

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